

Silicon N Channel MOS Type (U-MOSⅢ)

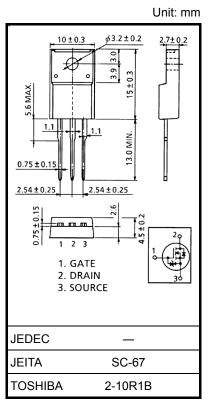
2SK3844

Switching Regulator, DC-DC Converter Applications Motor Drive Applications

- Low drain-source ON resistance: $RDS(ON) = 4.1 \text{ m}\Omega \text{ (typ.)}$
- High forward transfer admittance: $|Y_{fs}| = 63 \text{ S (typ.)}$
- Low leakage current: $IDSS = 100 \mu A (max)(VDS = 60 V)$
- Enhancement mode: $V_{th} = 2.0 \text{ to } 4.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA})$

Absolute Maximum Ratings (Ta = 25°C)

Characteristics			Symbol	Rating	Unit	
Drain-source voltage			V_{DSS}	60	V	
Drain-gate voltage ($R_{GS} = 20 \text{ k}\Omega$)			V_{DGR}	60	V	
Gate-source voltage			V _{GSS}	±20	V	
Drain current	DC (Note	1)	ΙD	45	Α	
Dialii cuileiit	Pulse (Note	1)	I_{DP}	180	A 	
Drain power dissipation (Tc=25°C)			P_{D}	45	W	
Single pulse avalanche energy (Note 2)		2)	E _{AS}	527	mJ	
Avalanche current			I _{AR}	45	Α	
Repetitive avalanche energy (Note 3)		3)	E _{AR}	4.0	mJ	
Channel temperature			T _{ch}	150	°C	
Storage temperature range			T _{stg}	-55~150	°C	



Weight: 1.9 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	2.78	°C/W
Thermal resistance, channel to ambient	R _{th (ch-a)}	62.5	°C/W

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: VDD = 25 V, Tch = 25°C (initial), L = 353 μ H, IAR = 45 A, RG = 25 Ω

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device. Please handle with caution.

Electrical Characteristics (Ta = 25°C)

Ch	Characteristics Symbol		Test Condition	Min	Тур.	Max	Unit
Gate leakage cui	rent	I _{GSS}	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±10	μА
Drain cut-off curr	ent	I _{DSS}	V _{DS} = 60 V, V _{GS} = 0 V		_	100	μΑ
Drain-source breakdown voltage		V (BR) DSS	$I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$	60	_	_	V
Drain-source bre	akuowii voilage	V (BR) DSX	$I_D = 10 \text{ mA}, V_{GS} = -20 \text{ V}$	35 — —		_	V
Gate threshold voltage	V _{th}	V _{DS} = 10 V, I _D = 1 mA	2.0	_	4.0	V	
Drain-source ON	resistance	R _{DS} (ON)	V _{GS} = 10 V, I _D = 23 A	_	4.1	5.8	mΩ
Forward transfer	admittance	Y _{fs}	V _{DS} = 10 V, I _D = 23 A		63	_	S
Input capacitance	acitance C _{iss}			_	12400	_	
Reverse transfer capacitance		C _{rss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz	_	700	_	pF
Output capacitan	Output capacitance			_	1100	_	
Switching time Fa	Rise time	t _r	V_{GS} $\stackrel{10}{{_{0}}{_{V}}}$ $\stackrel{1}{{_{D}}{_{D}}}$ $\stackrel{23}{{_{A}}$	_	18	_	ns
	Turn-on time	t _{on}		_	45	_	
	Fall time	tf		_	35	_	
	Turn-off time	t _{off}		_	200	_	
Total gate charge (gate-source plus		Qg		— 196 —			
Gate-source charge		Q _{gs}	$V_{DD} \simeq 48 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 45 \text{ A}$		148	_	nC
Gate-drain ("miller") charge		Q _{gd}			48	_	

Source-Drain Ratings and Characteristics (Ta = 25°C)

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (No	ote 1)	I _{DR} 1	_	_	_	45	Α
Pulse drain reverse current (No	ote 1)	I _{DRP}	_	_	_	180	Α
Forward voltage (diode)		V _{DSF}	I _{DR} = 45 A, V _{GS} = 0 V	_	_	-1.5	V
Reverse recovery time		t _{rr}	I _{DR} = 45 A, V _{GS} = 0 V,		67	_	ns
Reverse recovery charge		Qrr	dl _{DR} /dt = 50 A/μs	_	70	_	nC

Marking

